



## Material Content Data Sheet



Sales Product Name	TDA7110			Issued		28. August 2013		
MA#	MA000527274							
Package	PG-TSSOP-16-1			Weight*		59.70 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.497	2.51	2.51	25071	25071
leadframe	non noble metal	nickel	7440-02-0	8.109	13.58		135846	
	non noble metal	iron	7439-89-6	11.199	18.76	32.34	187596	323442
wire	noble metal	gold	7440-57-5	0.447	0.75	0.75	7480	7480
encapsulation	organic material	carbon black	1333-86-4	0.108	0.18		1815	
	plastics	epoxy resin	-	4.586	7.68		76825	
	inorganic material	silicondioxide	60676-86-0	31.417	52.64	60.50	526282	604923
leadfinish	non noble metal	tin	7440-31-5	0.915	1.53	1.53	15325	15325
plating	noble metal	silver	7440-22-4	0.856	1.43	1.43	14346	14346
glue	plastics	acrylic resin	-	0.124	0.21		2071	
	noble metal	silver	7440-22-4	0.438	0.73	0.94	7343	9414
*deviation	< 10%	Sum in total:				100,00		1000000

### Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com